

1000 BASE DUAL PORT SURFACE MOUNT MODULES MODEL NO.: IH-035

FEATURE:

RoHS Compliant

RoHS peak solder rating 260°C / 3~5 Sec

Designed to meet IR requirement

Specifications @ 25°C

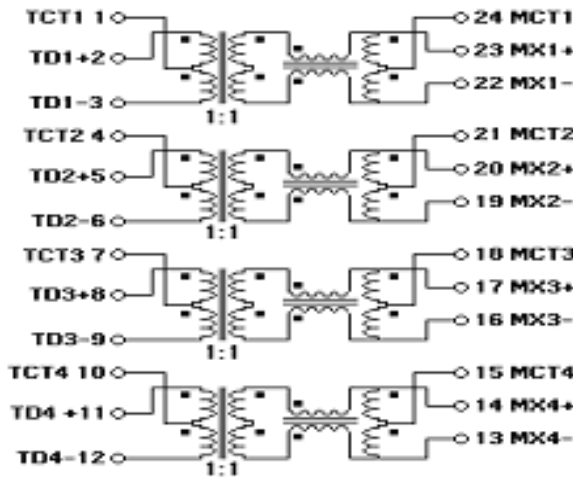
Operating temp. : 0°C ~ +70°C

OCL 350uH MIN. @100KHz 100mV 8mA VDC

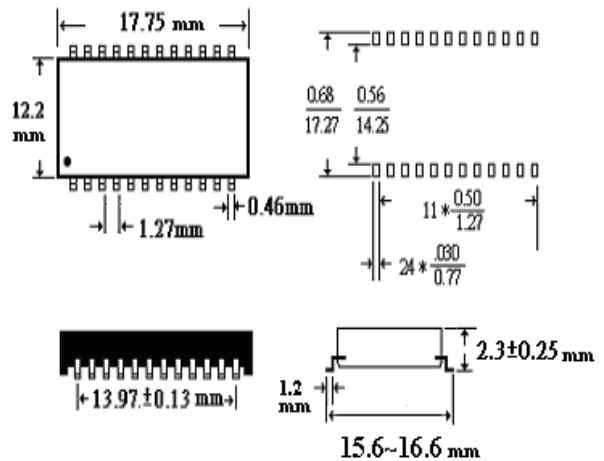
MSL=2

Part Number	Insertion Loss (dB MAX)	Return Loss (dB Min @100Ω)					Differential to Common Mode Rejection (dB MIN)			Cross talk (dB MIN)			Hi pot (Vrms MIN)
		1~100 MHz	1-30	40	50	60-80	100 MHz	30	60	100 MHz	30	60	
IH-035	1~100 MHz	1-30	40	50	60-80	100 MHz	30	60	100 MHz	30	60	100 MHz	1500
	1.0	-18	-14	-13	-12	-10	-43	-37	-33	-45	-40	-35	

SCHEMATICS:

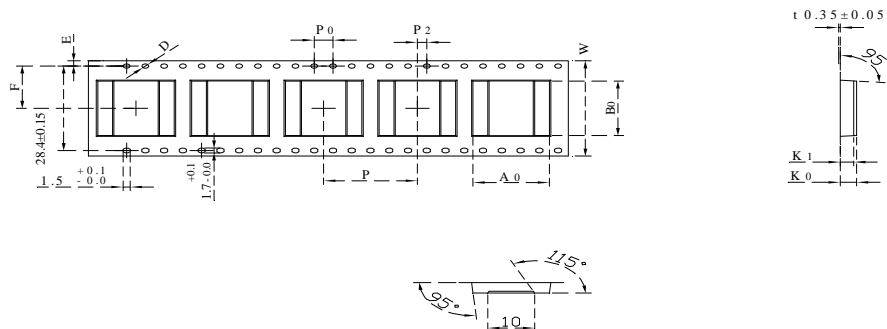


DIMENSION: mm TOLERANCE:±0.25



Packing :

ITEM	W	A ₀	B ₀	K ₀	K ₁	P	E	F	D	D ₁	P ₀	P ₂
DIM	32 ^{+0.3} _{-0.3}	16.3 ^{+0.1} _{-0.1}	18.3 ^{+0.1} _{-0.1}	3.5 ^{+0.1} _{-0.1}	2.9 ^{+0.1} _{-0.1}	20 ^{+0.1} _{-0.1}	1.75 ^{+0.1} _{-0.1}	14.2 ^{+0.1} _{-0.1}	1.5 ^{+0.1} _{-0.0}	0.0 ^{+0.25} _{-0.0}	4.0 ^{+0.1} _{-0.1}	2.0 ^{+0.1} _{-0.1}



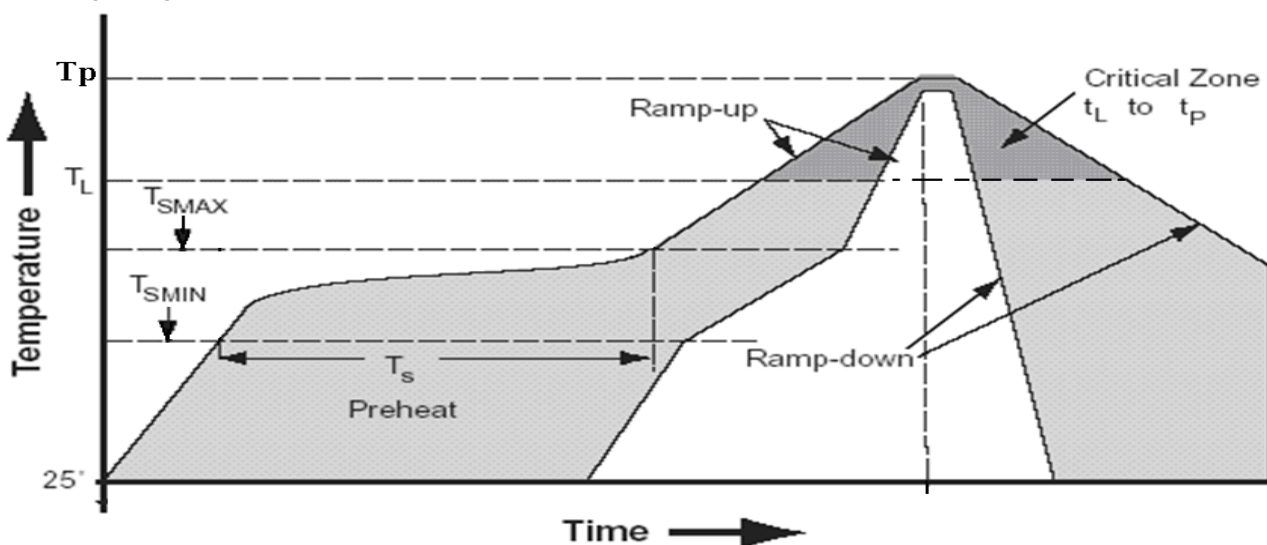
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Solder Reflow profile for Lead-Free packages.
Package Peak Reflow Temperatures

Classification Reflow Profiles

Profile Feature	Lead-Free Assembly	
Average ramp-up rate(T_L to T_P)	3°C / Second Max.	
Preheat Temperature Min.(T_s min.) Temperature Max.(T_s max.) Time (min to max) (T_s)	150 °C 200 °C 60-180 sec	
T_s max. to T_L Ramp-up Rate	3°C / Second Max.	
Time maintained above Temperature (T_L) Time (t_L)	217 °C 60-150 sec	
Peak Tempature (T_p) Time within 5 °C of actual peak Temp.	260 +0 / -5 °C 3 to 5 Sec	250 +0 / -5 °C 20 to 40 Sec
Ramp-down	6°C / Second Max.	
Time 25 °C to Peak Temperature	8 minutes Max.	

Profile



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PACKING

1. Tape & Reel : 800pcs / Reel , 4000pcs / Carton
2. Dry Pack : 1pcs
Product Description:(5g Silica Gel Desiccant)
PH: 4-8
Package Materials: Paper(Length 6.5±1cm , Width 5±1cm)
3. Reel Packed By Vacuum
4. Seal Per Jedec

